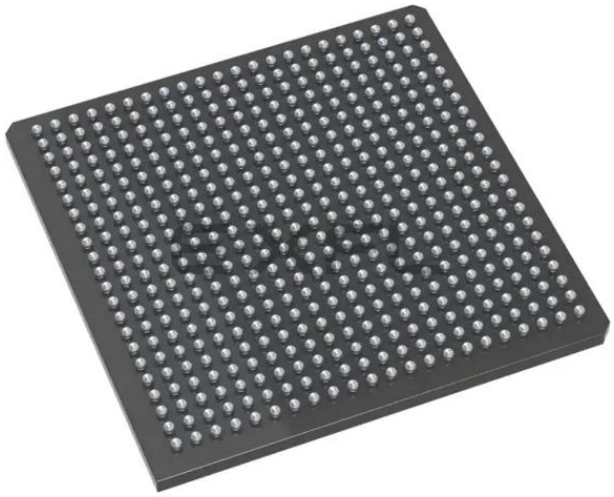

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	4224
Number of Logic Elements/Cells	-
Total RAM Bits	55296
Number of I/O	248
Number of Gates	250000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 70°C (TA)
Package / Case	484-BGA
Supplier Device Package	484-FPBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ax250-1fg484

Two C-cells, a single R-cell, two Transmit (TX), and two Receive (RX) routing buffers form a Cluster, while two Clusters comprise a SuperCluster (Figure 1-4). Each SuperCluster also contains an independent Buffer (B) module, which supports buffer insertion on high-fanout nets by the place-and-route tool, minimizing system delays while improving logic utilization.

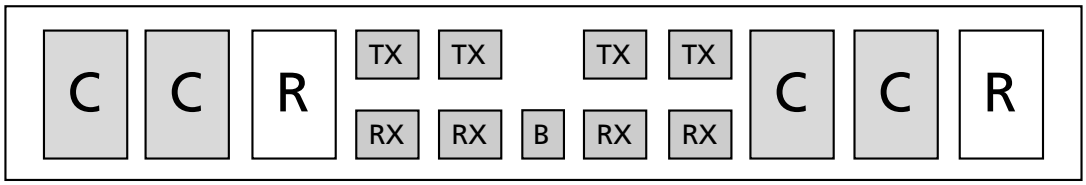

Figure 1-4 • **AX SuperCluster**

The logic modules within the SuperCluster are arranged so that two combinatorial modules are side-by-side, giving a C–C–R – C–C–R pattern to the SuperCluster. This C–C–R pattern enables efficient implementation (minimum delay) of two-bit carry logic for improved arithmetic performance (Figure 1-5 on page 1-3).

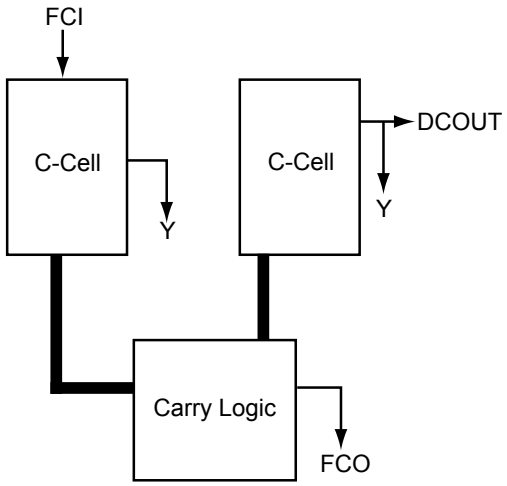

Figure 1-5 • **AX 2-Bit Carry Logic**

The AX architecture is fully fracturable, meaning that if one or more of the logic modules in a SuperCluster are used by a particular signal path, the other logic modules are still available for use by other paths.

At the chip level, SuperClusters are organized into core tiles, which are arrayed to build up the full chip. For example, the AX1000 is composed of a 3x3 array of nine core tiles. Surrounding the array of core tiles are blocks of I/O Clusters and the I/O bank ring (Table 1-1). Each core tile consists of an array of 336 SuperClusters and four SRAM blocks (176 SuperClusters and three SRAM blocks for the AX250).

Table 1-1 • **Number of Core Tiles per Device**

Device	Number of Core Tiles
AX125	1 regular tile
AX250	4 smaller tiles
AX500	4 regular tiles
AX1000	9 regular tiles
AX2000	16 regular tiles

Design Environment

The Axcelerator family of FPGAs is fully supported by both Microsemi's Libero® Integrated Design Environment and Designer FPGA Development software. Libero IDE is an integrated design manager that seamlessly integrates design tools while guiding the user through the design flow, managing all design and log files, and passing necessary design data among tools. Additionally, Libero IDE allows users to integrate both schematic and HDL synthesis into a single flow and verify the entire design in a single environment (see the *Libero IDE Flow* diagram located on the Microsemi SoC Products Group website). Libero IDE includes Synplify® Actel Edition (AE) from Synplicity®, ViewDraw® AE from Mentor Graphics®, ModelSim® HDL Simulator from Mentor Graphics, WaveFormer Lite™ AE from SynaptiCAD®, and Designer software from Microsemi.

Designer software is a place-and-route tool and provides a comprehensive suite of backend support tools for FPGA development. The Designer software includes the following:

- Timer – a world-class integrated static timing analyzer and constraints editor which support timing-driven place-and-route
- NetlistViewer – a design netlist schematic viewer
- ChipPlanner – a graphical floorplanner viewer and editor
- SmartPower – allows the designer to quickly estimate the power consumption of a design
- PinEditor – a graphical application for editing pin assignments and I/O attributes
- I/O Attribute Editor – displays all assigned and unassigned I/O macros and their attributes in a spreadsheet format

With the Designer software, a user can lock the design pins before layout while minimally impacting the results of place-and-route. Additionally, Microsemi's back-annotation flow is compatible with all the major simulators and the simulation results can be cross-probed with Silicon Explorer II, Microsemi's integrated verification and logic analysis tool. Another tool included in the Designer software is the SmartGen core generator, which easily creates popular and commonly used logic functions for implementation into your schematic or HDL design.

Designer software is compatible with the most popular FPGA design entry and verification tools from EDA vendors, such as Mentor Graphics, Synplicity, Synopsys, and Cadence Design Systems. The Designer software is available for both the Windows and UNIX operating systems.

Programming

Programming support is provided through Silicon Sculptor II, a single-site programmer driven via a PC-based GUI. In addition, BP Microsystems offers multi-site programmers that provide qualified support for Microsemi devices. Factory programming is available for high-volume production needs.

In-System Diagnostic and Debug Capabilities

The Axcelerator family of FPGAs includes internal probe circuitry, allowing the designer to dynamically observe and analyze any signal inside the FPGA without disturbing normal device operation (Figure 1-9).

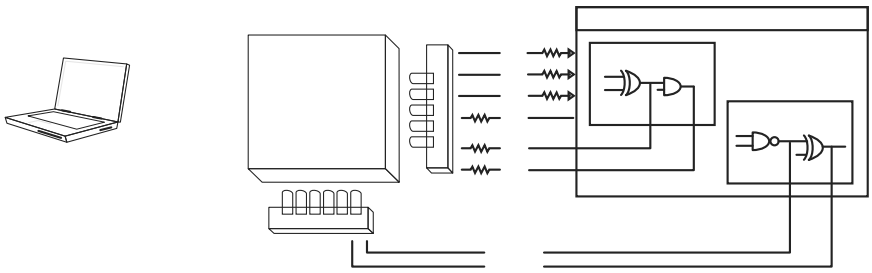

Figure 1-9 • **Probe Setup**

HSTL Class I

High-Speed Transceiver Logic is a general-purpose high-speed 1.5 V bus standard (EIA/JESD8-6). The Axcelerator devices support Class I. This requires a differential amplifier input buffer and a push-pull output buffer.

***Table 2-41* • DC Input and Output Levels**

VIL		VIH		VOL	VOH	IOL	IOH
Min., V	**Max., V**	**Min., V**	**Max., V**	**Max., V**	**Min., V**	**mA**	**mA**
-0.3	VREF – 0.1	VREF + 0.1	3.6	0.4	VCC – 0.4	8	-8

AC Loadings

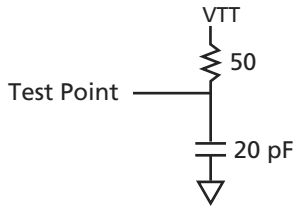

***Figure 2-20 •* AC Test Loads**

***Table 2-42* • AC Waveforms, Measuring Points, and Capacitive Loads**

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ) (V)	C_{load} (pF)
VREF –0.5	VREF + 0.5	VREF	0.75	20

*Note: * Measuring Point = VTRIP*

Timing Characteristics

***Table 2-43* • 1.5 V HSTL Class I I/O Module**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 1.425 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
1.5 V HSTL Class I I/O Module Timing								
t_{DP}	Input Buffer		1.80		2.05		2.41	ns
t_{PY}	Output Buffer		4.90		5.58		6.56	ns
t_{ICLKQ}	Clock-to-Q for the I/O input register		0.67		0.77		0.90	ns
t_{OCLKQ}	Clock-to-Q for the I/O output register and the I/O enable register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

SSTL2

Stub Series Terminated Logic for 2.5 V is a general-purpose 2.5 V memory bus standard (JESD8-9). The Axcelerator devices support both classes of this standard. This requires a differential amplifier input buffer and a push-pull output buffer.

Class I

***Table 2-44* • DC Input and Output Levels**

VIL		VIH		VOL	VOH	IOL	IOH
Min., V	**Max., V**	**Min., V**	**Max., V**	**Max., V**	**Min., V**	**mA**	**mA**
–0.3	VREF – 0.2	VREF + 0.2	3.6	VREF – 0.57	VREF + 0.57	7.6	–7.6

AC Loadings

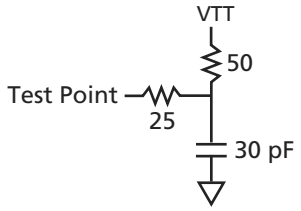

***Figure 2-21* • AC Test Loads**

***Table 2-45* • AC Waveforms, Measuring Points, and Capacitive Loads**

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ) (V)	C_{load} (pF)
VREF – 0.75	VREF + 0.75	VREF	1.25	30

*Note: * Measuring Point = VTRIP*

Timing Characteristics

***Table 2-46* • 2.5 V SSTL2 Class I I/O Module**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 2.3 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
2.5 V SSTL2 Class I I/O Module Timing								
t_{DP}	Input Buffer		1.83		2.08		2.45	ns
t_{PY}	Output Buffer		2.39		2.72		3.20	ns
t_{ICLKQ}	Clock-to-Q for the I/O input register		0.67		0.77		0.90	ns
t_{OCLKQ}	Clock-to-Q for the I/O output register and the I/O enable register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

Differential Standards

Physical Implementation

Implementing differential I/O standards requires the configuration of a pair of external I/O pads, resulting in a single internal signal. To facilitate construction of the differential pair, a single I/O Cluster contains the resources for a pair of I/Os. Configuration of the I/O Cluster as a differential pair is handled by Designer software when the user instantiates a differential I/O macro in the design.

Differential I/Os can also be used in conjunction with the embedded Input Register (InReg), Output Register (OutReg), Enable Register (EnReg), and Double Data Rate (DDR). However, there is no support for bidirectional I/Os or tristates with these standards.

LVDS

Low-Voltage Differential Signal (ANSI/TIA/EIA-644) is a high-speed, differential I/O standard. It requires that one data bit is carried through two signal lines, so two pins are needed. It also requires an external resistor termination. The voltage swing between these two signal lines is approximately 350 mV.

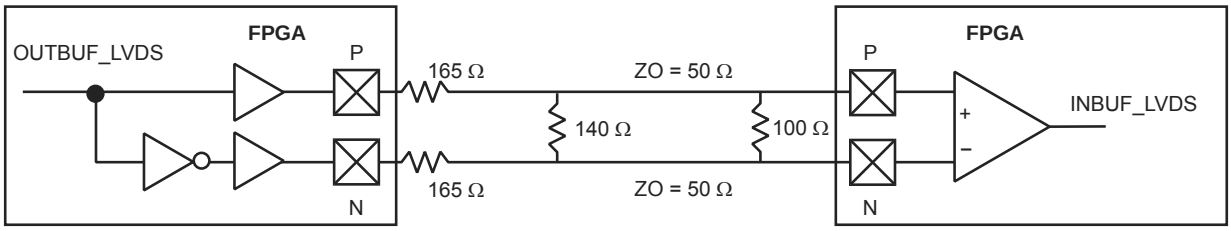

Figure 2-25 • **LVDS Board-Level Implementation**

The LVDS circuit consists of a differential driver connected to a terminated receiver through a constant-impedance transmission line. The receiver is a wide-common-mode-range differential amplifier. The common-mode range is from 0.2 V to 2.2 V for a differential input with 400 mV swing.

To implement the driver for the LVDS circuit, drivers from two adjacent I/O cells are used to generate the differential signals (note that the driver is not a current-mode driver). This driver provides a nominal constant current of 3.5 mA. When this current flows through a 100 Ω termination resistor on the receiver side, a voltage swing of 350 mV is developed across the resistor. The direction of the current flow is controlled by the data fed to the driver.

An external-resistor network (three resistors) is needed to reduce the voltage swing to about 350 mV. Therefore, four external resistors are required, three for the driver and one for the receiver.

Table 2-56 • **DC Input and Output Levels**

DC Parameter	Description	Min.	Typ.	Max.	Units
VCCI[1]	Supply Voltage	2.375	2.5	2.625	V
VOH	Output High Voltage	1.25	1.425	1.6	V
VOL	Output Low Voltage	0.9	1.075	1.25	V
VODIFF	Differential Output Voltage	250	350	450	mV
VOCM	Output Common Mode Voltage	1.125	1.25	1.375	V
VICM2	Input Common Mode Voltage	0.2	1.25	2.2	V

Notes:

1. *±5%*
2. *Differential input voltage = ±350 mV.*

Timing Characteristics

Table 2-65 • AX125 Predicted Routing Delays
Worst-Case Commercial Conditions VCCA = 1.425 V, T_J = 70°C

		–2 Speed	–1 Speed	Std Speed	
Parameter	**Description**	**Typical**	**Typical**	**Typical**	**Units**
Predicted Routing Delays					
t_{DC}	DirectConnect Routing Delay, FO1	0.11	0.12	0.15	ns
t_{FC}	FastConnect Routing Delay, FO1	0.35	0.39	0.46	ns
t_{RD1}	Routing delay for FO1	0.35	0.40	0.47	ns
t_{RD2}	Routing delay for FO2	0.38	0.43	0.51	ns
t_{RD3}	Routing delay for FO3	0.43	0.48	0.57	ns
t_{RD4}	Routing delay for FO4	0.48	0.55	0.64	ns
t_{RD5}	Routing delay for FO5	0.55	0.62	0.73	ns
t_{RD6}	Routing delay for FO6	0.64	0.72	0.85	ns
t_{RD7}	Routing delay for FO7	0.79	0.89	1.05	ns
t_{RD8}	Routing delay for FO8	0.88	0.99	1.17	ns
t_{RD16}	Routing delay for FO16	1.49	1.69	1.99	ns
t_{RD32}	Routing delay for FO32	2.32	2.63	3.10	ns

Table 2-66 • AX250 Predicted Routing Delays
Worst-Case Commercial Conditions VCCA = 1.425 V, T_J = 70°C

		–2 Speed	–1 Speed	Std Speed	
Parameter	**Description**	**Typical**	**Typical**	**Typical**	**Units**
Predicted Routing Delays					
t_{DC}	DirectConnect Routing Delay, FO1	0.11	0.12	0.15	ns
t_{FC}	FastConnect Routing Delay, FO1	0.35	0.39	0.46	ns
t_{RD1}	Routing delay for FO1	0.39	0.45	0.53	ns
t_{RD2}	Routing delay for FO2	0.41	0.46	0.54	ns
t_{RD3}	Routing delay for FO3	0.48	0.55	0.64	ns
t_{RD4}	Routing delay for FO4	0.56	0.63	0.75	ns
t_{RD5}	Routing delay for FO5	0.60	0.68	0.80	ns
t_{RD6}	Routing delay for FO6	0.84	0.96	1.13	ns
t_{RD7}	Routing delay for FO7	0.90	1.02	1.20	ns
t_{RD8}	Routing delay for FO8	1.00	1.13	1.33	ns
t_{RD16}	Routing delay for FO16	2.17	2.46	2.89	ns
t_{RD32}	Routing delay for FO32	3.55	4.03	4.74	ns

Global Resource Distribution

At the root of each global resource is a PLL. There are two groups of four PLLs for every device. One group, located at the center of the north edge (in the I/O ring) of the chip, sources the four HCLKs. The second group, located at the center of the south edge (again in the I/O ring), sources the four CLKs (Figure 2-38).

Regardless of the type of global resource, HCLK or CLK, each of the eight resources reach the ClockTileDist (CTD) Cluster located at the center of every core tile with zero skew. From the ClockTileDist Cluster, all four HCLKs and four CLKs are distributed through the core tile (Figure 2-39).

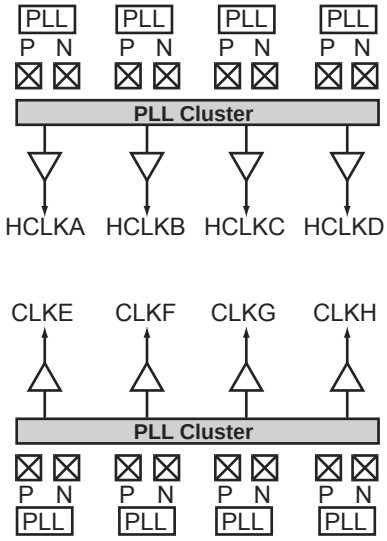

Figure 2-38 • **PLL Group**

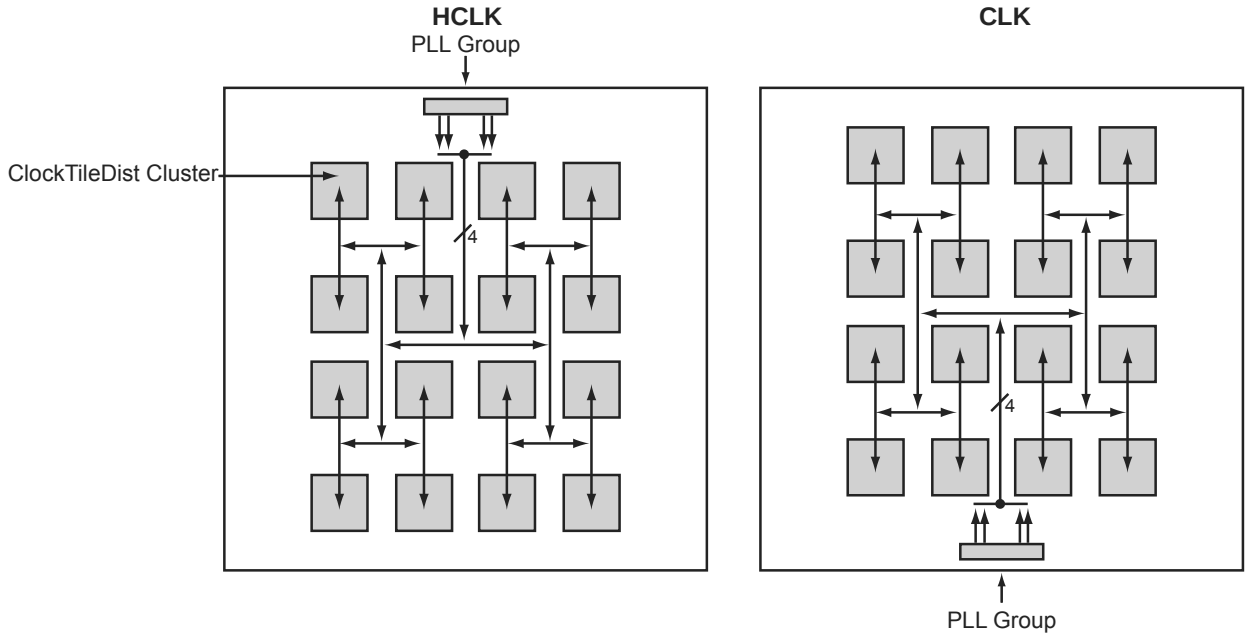

Figure 2-39 • **Example of HCLK and CLK Distributions on the AX2000**

***Table 2-90* • Two RAM Blocks Cascaded**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
Write Mode								
t_{WDASU}	Write Data Setup vs. WCLK		1.39		1.59		1.87	ns
t_{WDAHD}	Write Data Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WADSU}	Write Address Setup vs. WCLK		1.39		1.59		1.87	ns
t_{WADHD}	Write Address Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WENSU}	Write Enable Setup vs. WCLK		1.39		1.59		1.87	ns
t_{WENHD}	Write Enable Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WCKH}	WCLK Minimum High Pulse Width	0.75		0.75		0.75		ns
t_{WCLK}	WCLK Minimum Low Pulse Width	1.76		1.76		1.76		ns
t_{WCKP}	WCLK Minimum Period	2.51		2.51		2.51		ns
Read Mode								
t_{RADSU}	Read Address Setup vs. RCLK		1.71		1.94		2.28	ns
t_{RADHD}	Read Address Hold vs. RCLK		0.00		0.00		0.00	ns
t_{RENSU}	Read Enable Setup vs. RCLK		1.71		1.94		2.28	ns
t_{RENHD}	Read Enable Hold vs. RCLK		0.00		0.00		0.00	ns
$t_{RCK2RD1}$	RCLK-To-OUT (Pipelined)		1.43		1.63		1.92	ns
$t_{RCK2RD2}$	RCLK-To-OUT (Non-Pipelined)		2.26		2.58		3.03	ns
t_{RCLKH}	RCLK Minimum High Pulse Width	0.73		0.73		0.73		ns
t_{RCLKL}	RCLK Minimum Low Pulse Width	1.89		1.89		1.89		ns
t_{RCKP}	RCLK Minimum Period	2.62		2.62		2.62		ns

Note: Timing data for these two cascaded RAM blocks uses a depth of 8,192. For all other combinations, use Microsemi's timing software.

***Table 2-93* • Sixteen RAM Blocks Cascaded**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
Write Mode								
t_{WDASU}	Write Data Setup vs. WCLK		16.54		18.84		22.15	ns
t_{WDAHD}	Write Data Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WADSU}	Write Address Setup vs. WCLK		16.54		18.84		22.15	ns
t_{WADHD}	Write Address Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WENSU}	Write Enable Setup vs. WCLK		16.54		18.84		22.15	ns
t_{WENHD}	Write Enable Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WCKH}	WCLK Minimum High Pulse Width	0.75		0.75		0.75		ns
t_{WCLK}	WCLK Minimum Low Pulse Width	13.40		13.40		13.40		ns
t_{WCKP}	WCLK Minimum Period	14.15		14.15		14.15		ns
Read Mode								
t_{RADSU}	Read Address Setup vs. RCLK		18.13		20.65		24.27	ns
t_{RADHD}	Read Address Hold vs. RCLK		0.00		0.00		0.00	ns
t_{RENSU}	Read Enable Setup vs. RCLK		18.13		20.65		24.27	ns
t_{RENHD}	Read Enable Hold vs. RCLK		0.00		0.00		0.00	ns
$t_{RCK2RD1}$	RCLK-To-OUT (Pipelined)		12.08		13.76		16.17	ns
$t_{RCK2RD2}$	RCLK-To-OUT (Non-Pipelined)		12.83		14.62		17.18	ns
t_{RCLKH}	RCLK Minimum High Pulse Width	0.73		0.73		0.73		ns
t_{RCLKL}	RCLK Minimum Low Pulse Width	14.41		14.41		14.41		ns
t_{RCKP}	RCLK Minimum Period	15.14		15.14		15.14		ns

Note: Timing data for these sixteen cascaded RAM blocks uses a depth of 65,536. For all other combinations, use Microsemi's timing software.

mode if desired. Please note, if the I/O bank is not disabled, differential I/Os belonging to the I/O bank will still consume normal power, even when operating in the low power mode.

The Axcelerator device will resume normal operation 10µs after the LP pin is pulled Low.

To further reduce power consumption, the internal charge pump can be bypassed and an external power supply voltage can be used instead. This saves the internal charge-pump operating current, resulting in no DC current draw. The Axcelerator family devices have a dedicated "V_{PUMP}" pin that can be used to access an external charge pump device. In normal chip operation, when using the internal charge pump, V_{PUMP} should be tied to GND. When the voltage level on V_{PUMP} is set to 3.3V, the internal charge pump is turned off, and the V_{PUMP} voltage will be used as the charge pump voltage. Adequate voltage regulation (i.e. high drive, low output impedance, and good decoupling) should be used at V_{PUMP}.

In addition, any PLL in use can be powered down to further reduce power consumption. This can be done with the PowerDown pin driven Low. Driving this pin High restarts the PLL with the output clock(s) being stable once lock is restored.

JTAG

Axcelerator offers a JTAG interface that is compliant with the IEEE 1149.1 standard. The user can employ the JTAG interface for probing a design and performing any JTAG Public Instructions as defined in the Table 2-103.

***Table 2-103* • JTAG Instruction Code**

Instruction (IR4:IR0)	Binary Code
Extest	00000
Preload / Sample	00001
Intest	00010
USERCODE	00011
IDCODE	00100
HIGHZ	01110
CLAMP	01111
Diagnostic	10000
Reserved	All others
Bypass	11111

Interface

The interface consists of four inputs: Test Mode Select (TMS), Test Data In (TDI), Test Clock (TCK), TAP Controller Reset (TRST), and an output, Test Data Out (TDO). TMS, TDI, and TRST have on-chip pull-up resistors.

TRST

TRST (Test-Logic Reset) is an active-low, asynchronous reset signal to the TAP controller. The TRST input can be used to reset the Test Access Port (TAP) Controller to the TRST state. The TAP Controller can be held at this state permanently by grounding the TRST pin. To hold the JTAG TAP controller in the TRST state, it is recommended to connect TRST to ground via a 1 kΩ resistor.

There is an optional internal pull-up resistor available for the TRST input that can be set by the user at programming. Care should be exercised when using this option in combination with an external tie-off to ground.

An on-chip power-on-reset (POWRST) circuit is included. POWRST has the same function as "TRST," but it only occurs at power-up or during recovery from a VCCA and/or VCCDA voltage drop.

TDO

TDO is normally tristated, and it is active only when the TAP controller is in the "Shift_DR" state or "Shift_IR" state. The least significant bit of the selected register (i.e. IR or DR) is clocked out to TDO first by the falling edge of TCK.

TAP Controller

The TAP Controller is compliant with the IEEE Standard 1149.1. It is a state machine of 16 states that controls the Instruction Register (IR) and the Data Registers (such as BSR, IDCODE, USRCODE, BYPASS, etc.). The TAP Controller steps into one of the states depending on the sequence of TMS at the rising edges of TCK.

Instruction Register (IR)

The IR has five bits (IR4 to IR0). At the TRST state, IR is reset to IDCODE. Each time when IR is selected, it goes through "select IR-Scan," "Capture-IR," "Shift-IR," all the way through "Update-IR." When there is no test error, the first five data bits coming out of TDO during the "Shift-IR" will be "10111". If a test error occurs, the last three bits will contain one to three zeroes corresponding to negatively asserted signals: "TDO_ERRORB," "PROBA_ERRORB," and "PROBB_ERRORB." The error(s) will be erased when the TAP is at the "Update-IR" or the TRST state. When in user mode start-up sequence, if the micro-probe has not been used, the "PROBA_ERRORB" is used as a "Power-up done successfully" flag.

Data Registers (DRs)

Data registers are distributed throughout the chip. They store testing/programming vectors. The MSB of a data register is connected to TDI, while the LSB is connected to TDO. There are different types of data registers. Descriptions of the main registers are as follow:

1. IDCODE:

   The IDCODE is a 20-bit hard coded JTAG Silicon Signature. It is a hardwired device ID code, which contains the Microsemi identity, part number, and version number in a specific JTAG format.

2. USERCODE:

   The USERCODE is a 33-bit programmable register. However, only 20 bits are allocated to use as JTAG Silicon Signature. It is a supplementary identity code for the user to program information to distinguish different programmed parts. USERCODE fuses will read out as "zeroes" when not programmed, so only the "1" bits need to be programmed.

3. Boundary-Scan Register (BSR):

   Each I/O contains three Boundary-Scan Cells. Each cell has a shift register bit, a latch, and two MUXes. The boundary-scan cells are used for the Output-enable (E), Output (O), and Input (I) registers. The bit order of the boundary-scan cells for each of them is E-O-I. The boundary-scan cells are then chained serially to form the Boundary-Scan Register (BSR). The length of the BSR is the number of I/Os in the die multiplied by three.

4. Bypass Register (BYR):

   This is the "1-bit" register. It is used to shorten the TDI-TDO serial chain in board-level testing to only one bit per device not being tested. It is also selected for all "reserved" or unused instructions.

Probing

Internal activities of the JTAG interface can be observed via the Silicon Explorer II probes: "PRA," "PRB," "PRC," and "PRD."

Special Fuses

Security

Microsemi antifuse FPGAs, with FuseLock technology, offer the highest level of design security available in a programmable logic device. Since antifuse FPGAs are live-at power-up, there is no bitstream that can be intercepted, and no bitstream or programming data is ever downloaded to the device during power-up, thus protecting against device cloning. In addition, special security fuses are hidden

FG256-Pin FBGA	
AX125 Function	**Pin Number**
VCCA	L10
VCCA	L7
VCCA	L8
VCCA	L9
VCCA	N3
VCCA	P14
VCCPLA	C7
VCCPLB	D6
VCCPLC	A10
VCCPLD	D10
VCCPLE	P10
VCCPLF	N11
VCCPLG	T7
VCCPLH	N7
VCCDA	A2
VCCDA	C13
VCCDA	D9
V_{CCDA}	H1
VCCDA	J15
VCCDA	N14
VCCDA	N8
VCCDA	P4
VCCIB0	E6
VCCIB0	E7
VCCIB0	E8
VCCIB1	E10
VCCIB1	E11
VCCIB1	E9
VCCIB2	F12
VCCIB2	G12
VCCIB2	H12
VCCIB3	J12
VCCIB3	K12
VCCIB3	L12
VCCIB4	M10

FG256-Pin FBGA	
AX125 Function	**Pin Number**
VCCIB4	M11
VCCIB4	M9
VCCIB5	M6
VCCIB5	M7
VCCIB5	M8
VCCIB6	J5
VCCIB6	K5
VCCIB6	L5
VCCIB7	F5
VCCIB7	G5
VCCIB7	H5
VCOMPLA	A7
VCOMPLB	D7
VCOMPLC	B9
VCOMPLD	D11
VCOMPLE	T10
VCOMPLF	N10
VCOMPLG	R8
VCOMPLH	N6
VPUMP	A14

FG484	
AX250 Function	**Pin Number**
IO104PB6F6	N4
IO105NB6F6	M5
IO105PB6F6	N5
IO106NB6F6	M3
IO106PB6F6	N3
Bank 7	
IO107NB7F7	M2
IO107PB7F7	N1
IO108NB7F7	L3
IO108PB7F7	L2
IO109NB7F7	K2
IO109PB7F7	K1
IO110NB7F7	K5
IO110PB7F7	L5
IO111NB7F7	K6
IO111PB7F7	L6
IO112NB7F7	K4
IO112PB7F7	K3
IO113NB7F7	K7
IO113PB7F7	L7
IO114NB7F7	H1
IO114PB7F7	J1
IO115NB7F7	H2
IO115PB7F7	J2
IO116NB7F7	H4
IO116PB7F7	J4
IO117NB7F7	H5
IO117PB7F7	J5
IO118NB7F7	F2
IO118PB7F7	G2
IO119NB7F7	H6
IO119PB7F7	J6
IO120NB7F7	F1
IO120PB7F7	G1
IO121NB7F7	F4
IO121PB7F7	G4

FG484	
AX250 Function	**Pin Number**
IO122NB7F7	G5
IO122PB7F7	G6
IO123NB7F7	F5
IO123PB7F7	E4
Dedicated I/O	
VCCDA	H7
GND	A1
GND	A11
GND	A12
GND	A2
GND	A21
GND	A22
GND	AA1
GND	AA2
GND	AA21
GND	AA22
GND	AB1
GND	AB11
GND	AB12
GND	AB2
GND	AB21
GND	AB22
GND	B1
GND	B2
GND	B21
GND	B22
GND	C20
GND	C3
GND	D19
GND	D4
GND	E18
GND	E5
GND	G18
GND	H15
GND	H8
GND	J14

FG484	
AX250 Function	**Pin Number**
GND	J9
GND	K10
GND	K11
GND	K12
GND	K13
GND	L1
GND	L10
GND	L11
GND	L12
GND	L13
GND	L22
GND	M1
GND	M10
GND	M11
GND	M12
GND	M13
GND	M22
GND	N10
GND	N11
GND	N12
GND	N13
GND	P14
GND	P9
GND	R15
GND	R8
GND	U16
GND	U6
GND	V18
GND	V5
GND	W19
GND	W4
GND	Y20
GND	Y3
GND/LP	G7
NC	A17
NC	A18

FG484	
AX250 Function	**Pin Number**
NC	A19
NC	A4
NC	A5
NC	AA11
NC	AA12
NC	AA18
NC	AA19
NC	AA4
NC	AB16
NC	AB17
NC	AB4
NC	AB7
NC	AB8
NC	B11
NC	B12
NC	B17
NC	B18
NC	B19
NC	B4
NC	B5
NC	C10
NC	C11
NC	C14
NC	C15
NC	C18
NC	C19
NC	D1
NC	D2
NC	D21
NC	D3
NC	E1
NC	E2
NC	E21
NC	E3
NC	F22
NC	F3

FG484	
AX250 Function	**Pin Number**
NC	G22
NC	G3
NC	H3
NC	J3
NC	K21
NC	K22
NC	N22
NC	P22
NC	R19
NC	R22
NC	T1
NC	T22
NC	U1
NC	U2
NC	U21
NC	U22
NC	V1
NC	V2
NC	V21
NC	V22
NC	V3
NC	W1
NC	W2
NC	W21
NC	W22
NC	W3
NC	Y10
NC	Y11
NC	Y12
NC	Y13
NC	Y15
NC	Y16
NC	Y17
NC	Y18
NC	Y8
NC	Y9

FG484	
AX250 Function	**Pin Number**
PRA	G11
PRB	F11
PRC	T12
PRD	U12
TCK	G8
TDI	F9
TDO	F7
TMS	F6
TRST	F8
VCCA	G17
VCCA	J10
VCCA	J11
VCCA	J12
VCCA	J13
VCCA	J7
VCCA	K14
VCCA	K9
VCCA	L14
VCCA	L9
VCCA	M14
VCCA	M9
VCCA	N14
VCCA	N9
VCCA	P10
VCCA	P11
VCCA	P12
VCCA	P13
VCCA	T6
VCCA	U17
VCCPLA	F10
VCCPLB	G9
VCCPLC	D13
VCCPLD	G13
VCCPLE	U13
VCCPLF	T14
VCCPLG	W10

FG676	
AX1000 Function	**Pin Number**
Bank 0	
IO00NB0F0	B4
IO00PB0F0	C4
IO02NB0F0	E7
IO02PB0F0	E6
IO03NB0F0	D6
IO03PB0F0	D5
IO04NB0F0	B5
IO04PB0F0	C5
IO05NB0F0	A5
IO05PB0F0	A4
IO06NB0F0	F7
IO06PB0F0	F6
IO07NB0F0	B6
IO07PB0F0	C6
IO08NB0F0	C7
IO08PB0F0	D7
IO10NB0F0	F8
IO10PB0F0	E8
IO11NB0F0	A7
IO11PB0F0	A6
IO12NB0F1	C8
IO12PB0F1	D8
IO13NB0F1	B8
IO13PB0F1	B7
IO14NB0F1	D9
IO14PB0F1	E9
IO16NB0F1	F10
IO16PB0F1	F9
IO18NB0F1	B9
IO18PB0F1	C9
IO19NB0F1	A10
IO19PB0F1	A9
IO20NB0F1	D10
IO20PB0F1	E10
IO21NB0F1	B10

FG676	
AX1000 Function	**Pin Number**
IO21PB0F1	C10
IO22NB0F2	F11
IO22PB0F2	G11
IO24NB0F2	D11
IO24PB0F2	E11
IO26NB0F2	C12
IO26PB0F2	C11
IO28NB0F2	F12
IO28PB0F2	G12
IO30NB0F2/HCLKAN	A12
IO30PB0F2/HCLKAP	B12
IO31NB0F2/HCLKBN	C13
IO31PB0F2/HCLKBP	B13
Bank 1	
IO32NB1F3/HCLKCN	C15
IO32PB1F3/HCLKCP	C14
IO33NB1F3/HCLKDN	A15
IO33PB1F3/HCLKDP	B15
IO35NB1F3	B16
IO35PB1F3	A16
IO36NB1F3	F15
IO36PB1F3	G15
IO38NB1F3	F16
IO38PB1F3	G16
IO40NB1F3	A18
IO40PB1F3	A17
IO41NB1F4	C18
IO41PB1F4	C17
IO42NB1F4	D16
IO42PB1F4	E16
IO44NB1F4	D18
IO44PB1F4	D17
IO45NB1F4	B19
IO45PB1F4	B18
IO46NB1F4	B20
IO46PB1F4	A20

FG676	
AX1000 Function	**Pin Number**
IO48NB1F4	F17
IO48PB1F4	E17
IO49NB1F4	A22
IO49PB1F4	A21
IO50NB1F4	E18
IO50PB1F4	F18
IO51NB1F4	D19
IO51PB1F4	C19
IO52NB1F4	D20
IO52PB1F4	C20
IO54NB1F5	B22
IO54PB1F5	B21
IO55NB1F5	D21
IO55PB1F5	C21
IO56NB1F5	F19
IO56PB1F5	E19
IO57NB1F5	B23
IO57PB1F5	A23
IO58NB1F5	D22
IO58PB1F5	C22
IO59NB1F5	B24
IO59PB1F5	A24
IO60NB1F5	E21
IO60PB1F5	E20
IO62NB1F5	D23
IO62PB1F5	C23
IO63NB1F5	F21
IO63PB1F5	F20
Bank 2	
IO64NB2F6	H21
IO64PB2F6	G21
IO65NB2F6	G22
IO65PB2F6	F22
IO66NB2F6	F24
IO66PB2F6	F23
IO67NB2F6	E24

FG896	
AX2000 Function	Pin Number
GND	AK18
GND	AK2
GND	AK23
GND	AK29
GND	AK8
GND	B1
GND	B2
GND	B22
GND	B29
GND	B30
GND	B9
GND	C10
GND	C15
GND	C16
GND	C21
GND	C28
GND	C3
GND	D27
GND	D28
GND	D4
GND	E26
GND	E5
GND	H1
GND	H30
GND	J2
GND	J22
GND	J29
GND	J9
GND	K10
GND	K21
GND	K28
GND	K3
GND	L11
GND	L20
GND	M12

FG896	
AX2000 Function	Pin Number
GND	M13
GND	M14
GND	M15
GND	M16
GND	M17
GND	M18
GND	M19
GND	N1
GND	N12
GND	N13
GND	N14
GND	N15
GND	N16
GND	N17
GND	N18
GND	N19
GND	N30
GND	P12
GND	P13
GND	P14
GND	P15
GND	P16
GND	P17
GND	P18
GND	P19
GND	R12
GND	R13
GND	R14
GND	R15
GND	R16
GND	R17
GND	R18
GND	R19
GND	R28
GND	R3

FG896	
AX2000 Function	Pin Number
GND	T12
GND	T13
GND	T14
GND	T15
GND	T16
GND	T17
GND	T18
GND	T19
GND	T28
GND	T3
GND	U12
GND	U13
GND	U14
GND	U15
GND	U16
GND	U17
GND	U18
GND	U19
GND	V1
GND	V12
GND	V13
GND	V14
GND	V15
GND	V16
GND	V17
GND	V18
GND	V19
GND	V30
GND	W12
GND	W13
GND	W14
GND	W15
GND	W16
GND	W17
GND	W18

FG896	
AX2000 Function	Pin Number
VCCIB3	AH30
VCCIB3	T21
VCCIB3	U21
VCCIB3	V21
VCCIB3	W21
VCCIB3	W22
VCCIB3	Y21
VCCIB3	Y22
VCCIB4	AA16
VCCIB4	AA17
VCCIB4	AA18
VCCIB4	AA19
VCCIB4	AA20
VCCIB4	AB19
VCCIB4	AB20
VCCIB4	AB21
VCCIB4	AJ28
VCCIB4	AK28
VCCIB5	AA11
VCCIB5	AA12
VCCIB5	AA13
VCCIB5	AA14
VCCIB5	AA15
VCCIB5	AB10
VCCIB5	AB11
VCCIB5	AB12
VCCIB5	AJ3
VCCIB5	AK3
VCCIB6	AA9
VCCIB6	AH1
VCCIB6	AH2
VCCIB6	T10
VCCIB6	U10
VCCIB6	V10
VCCIB6	W10

FG896	
AX2000 Function	Pin Number
VCCIB6	W9
VCCIB6	Y10
VCCIB6	Y9
VCCIB7	C1
VCCIB7	C2
VCCIB7	K9
VCCIB7	L10
VCCIB7	L9
VCCIB7	M10
VCCIB7	M9
VCCIB7	N10
VCCIB7	P10
VCCIB7	R10
VCCPLA	G14
VCCPLB	H15
VCCPLC	G17
VCCPLD	J16
VCCPLE	AH17
VCCPLF	AC16
VCCPLG	AH14
VCCPLH	AD15
VCOMPLA	F14
VCOMPLB	J15
VCOMPLC	F17
VCOMPLD	H16
VCOMPLE	AF17
VCOMPLF	AD16
VCOMPLG	AF14
VCOMPLH	AB15
VPUMP	G24

CQ352	
AX500 Function	Pin Number
VCCDA	346
VCCIB0	321
VCCIB0	333
VCCIB0	344
VCCIB1	273
VCCIB1	285
VCCIB1	297
VCCIB2	227
VCCIB2	239
VCCIB2	245
VCCIB2	257
VCCIB3	185
VCCIB3	197
VCCIB3	203
VCCIB3	215
VCCIB4	144
VCCIB4	156
VCCIB4	168
VCCIB5	96
VCCIB5	108
VCCIB5	120
VCCIB6	50
VCCIB6	62
VCCIB6	68
VCCIB6	80
VCCIB7	8
VCCIB7	20
VCCIB7	26
VCCIB7	38
VCCPLA	317
VCCPLB	315
VCCPLC	303
VCCPLD	301
VCCPLE	140
VCCPLF	138

CQ352	
AX500 Function	Pin Number
VCCPLG	126
VCCPLH	124
VCOMPLA	318
VCOMPLB	316
VCOMPLC	304
VCOMPLD	302
VCOMPLE	141
VCOMPLF	139
VCOMPLG	127
VCOMPLH	125
VPUMP	267

CG624	
AX1000 Function	**Pin Number**
IO63PB1F5	G18
Bank 2	
IO64NB2F6	M17
IO64PB2F6	G22
IO65NB2F6	J21
IO65PB2F6	J20
IO66NB2F6	L23
IO66PB2F6	K20
IO67NB2F6	F23
IO67PB2F6	E23
IO68NB2F6	L18
IO68PB2F6	K18
IO70NB2F6	E24
IO70PB2F6	D24
IO71NB2F6	H23
IO71PB2F6	G23
IO72NB2F6	L19
IO72PB2F6	K19
IO74NB2F7	J22
IO74PB2F7	H22
IO75NB2F7	N23
IO75PB2F7	M23
IO76NB2F7	N17
IO76PB2F7	N16
IO77NB2F7	L22
IO77PB2F7	K22
IO78NB2F7	M19
IO78PB2F7	M18
IO79NB2F7	N19
IO79PB2F7	N18
IO80NB2F7	L21
IO80PB2F7	L20
IO82NB2F7	P18
IO82PB2F7	P17
IO83NB2F7	N22
IO83PB2F7	M22

CG624	
AX1000 Function	**Pin Number**
IO84NB2F7	M20
IO84PB2F7	M21
IO86NB2F8	E25
IO86PB2F8	D25
IO87NB2F8	L24
IO87PB2F8	K24
IO88NB2F8	G24
IO88PB2F8	F24
IO89NB2F8	J25
IO90NB2F8	G25
IO90PB2F8	F25
IO91NB2F8	L25
IO91PB2F8	K25
IO92NB2F8	J24
IO92PB2F8	H24
IO93PB2F8	J23
IO94NB2F8	N24
IO94PB2F8	M24
IO95NB2F8	N25
IO95PB2F8	M25
Bank 3	
IO96NB3F9	T18
IO96PB3F9	R18
IO97NB3F9	N20
IO97PB3F9	P24
IO98NB3F9	P20
IO98PB3F9	P19
IO99NB3F9	P21
IO100NB3F9	T22
IO100PB3F9	W24
IO101NB3F9	R22
IO101PB3F9	P22
IO102NB3F9	U19
IO102PB3F9	T19
IO104NB3F9	V20
IO104PB3F9	U20

CG624	
AX1000 Function	**Pin Number**
IO105NB3F9	R23
IO105PB3F9	P23
IO106NB3F9	R19
IO106PB3F9	R20
IO107NB3F10	AB24
IO108NB3F10	R25
IO108PB3F10	P25
IO109NB3F10	U25
IO109PB3F10	T25
IO110NB3F10	U24
IO110PB3F10	U23
IO112NB3F10	T24
IO112PB3F10	R24
IO113NB3F10	Y25
IO113PB3F10	W25
IO114NB3F10	V23
IO114PB3F10	V24
IO116NB3F10	AA24
IO116PB3F10	Y24
IO117NB3F10	AB25
IO117PB3F10	AA25
IO118NB3F11	T20
IO118PB3F11	R21
IO120NB3F11	W22
IO120PB3F11	W23
IO122NB3F11	V22
IO122PB3F11	U22
IO124NB3F11	Y23
IO124PB3F11	AA23
IO126NB3F11	V21
IO126PB3F11	U21
IO128NB3F11	Y22
IO128PB3F11	Y21
Bank 4	
IO129NB4F12	W20
IO129PB4F12	Y20

Revision	Changes	Page
Revision 17 (continued)	The C180 package was removed from product tables and the "Package Pin Assignments" section (PDN 0909).	3-1
	Package names used in the"Axcelerator Family Product Profile" and "Package Pin Assignments" section were revised to match standards given in *Package Mechanical Drawings* (SAR 27395).	i, 3-1
	The "Introduction" section for "User I/Os" was updated as follows: "The user does not need to assign VREF pins for OUTBUF and TRIBUF. VREF pins are needed only for input and bidirectional I/Os" (SARs 24181, 24309).	2-11
	Power values in Table 2-4 • Default CLOAD/VCCI were updated to reflect those of SmartPower (SAR 33945).	2-3
	Two parameter names were corrected in Figure 2-10 • Output Buffer Delays. One occurrence of t_{ENLZ} was changed to t_{ENZL} and one occurrence of t_{ENHZ} was changed to t_{ENZH} (SAR 33890).	2-22
	The "Timing Model" section was updated with new timing values. Timing tables in the "I/O Specifications" section were updated to include enable paths. Values in the timing tables in the "Voltage-Referenced I/O Standards" section and "Differential Standards" section were updated. Table 2-63 • R-Cell was updated (SAR 33945).	2-8, 2-26 to 2-53
	Figure 2-11 • Timing Model was replaced (SAR 33043).	2-23
	The timing tables for "RAM" and "FIFO" were updated (SAR 33945).	2-90 to 2-106
	"Data Registers (DRs)" values were modified for IDCODE and USERCODE (SARs 18257, 26406).	2-108
	The package diagram for the "CQ208" package was incorrect and has been replaced with the correct diagram (SARs 23865, 26345).	3-89
Revision 16 (v2.8, Oct. 2009)	The datasheet was updated to include AX2000-CQ2526 information.	N/A
	MIL-STD-883 Class B is no longer supported by Axcelerator FPGAs and as a result was removed.	N/A
	A footnote was added to the "Introduction" in the "Axcelerator Clock Management System" section.	2-75
Revision 15 (v2.7, Nov. 2008)	RoHS-compliant information was added to the "Ordering Information".	ii
	ACTgen was changed to SmartGen because ACTgen is obsolete.	N/A
Revision 14 (v2.6)	In Table 2-4, the units for the P_{LOAD}, P_{10}, and $P_{I/O}$ were updated from mW/MHz to mW/MHz.	2-3
	In the "Pin Descriptions"section, the HCLK and CLK descriptions were updated to include tie-off information.	2-9
	The "Global Resource Distribution" section was updated.	2-70
	The " CG624" table was updated.	3-116
Revision 13 (v2.5)	A note was added to Table 2-2.	2-1
	In the "Package Thermal Characteristics", the temperature was changed from 150°C to 125°C.	2-6